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FDW262P

20V P-Channel PowerTrench® MOSFET

General Description

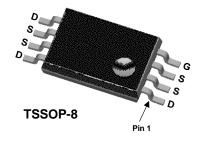
This P-Channel 1.8V specified MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

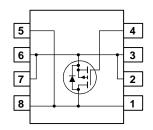
Applications

- Power management
- Load switch

Features

- -4.5 A, -20 V. $R_{DS(ON)} = 47 \ m\Omega \ @V_{GS} = -4.5 \ V$ $R_{DS(ON)} = 65 \ m\Omega \ @V_{GS} = -2.5 \ V$ $R_{DS(ON)} = 100 \ m\Omega \ @V_{GS} = -1.8 \ V$
- R_{DS(ON)} rated for use with 1.8 V logic
- Low gate charge (13nC typical)
- High performance trench technology for extremely low $R_{\mbox{\scriptsize DS(ON)}}$
- Low profile TSSOP-8 package





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		±8	V
I _D	Drain Current - Continuous	(Note 1a)	-4.5	А
	– Pulsed		-40	
P _D	Power Dissipation for Single Operation	(Note 1a)	1.3	W
		(Note 1b)	0.6	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	87	°C/W
		(Note 1b)	133	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
262P	FDW262P	13"	16mm	2500 units

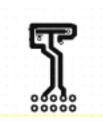
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics	1		l	l	l
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-20			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$, Referenced to 25°C		-14		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μΑ
I _{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 8 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -8 \text{ V}$ $V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)			•	•	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-0.4	-0.8	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I _D = -250 μA, Referenced to 25°C		2.5		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$		37 50 77 48	47 65 100 65	mΩ
I _{D(on)}	On-State Drain Current	$V_{GS} = -4.5 \text{ V}, \qquad V_{DS} = -5 \text{ V}$	-20			Α
g _{FS}	Forward Transconductance	$V_{DS} = -5 \text{ V}, \qquad I_{D} = -4.5 \text{ A}$		16		S
Dvnamic	Characteristics			•	•	
C _{iss}	Input Capacitance	$V_{DS} = -10 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		1193		pF
Coss	Output Capacitance	f = 1.0 MHz		193		pF
C _{rss}	Reverse Transfer Capacitance			96		pF
Switchin	ng Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -10 \text{ V}, \qquad I_{D} = -1 \text{ A}, \ V_{GS} = -4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		11	20	ns
t _r	Turn-On Rise Time			9	18	ns
t _{d(off)}	Turn-Off Delay Time			36	57	ns
t _f	Turn-Off Fall Time			19	34	ns
Q _g	Total Gate Charge	$V_{DS} = -10 \text{ V}, \qquad I_{D} = -4.5 \text{ A},$		13	18	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = -4.5 \text{ V}$		2.5		nC
Q _{gd}	Gate-Drain Charge	7		3.6		nC
Drain-Se	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain-Source				-1.1	Α
V _{SD}	Drain-Source Diode Forward	$V_{GS} = 0 \text{ V}, I_S = -1.1 \text{ A} \text{(Note 2)}$		-0.7	-1.2	V

Notes:

1. R_{8JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{8JC} is guaranteed by design while R_{8CA} is determined by the user's board design.



a) 87°C/W when mounted on a 1in² pad of 2 oz copper.



b) 133°C/W when mounted on a minimum pad of 2 oz copper.

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

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Typical Characteristics

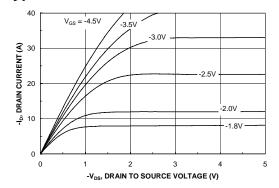
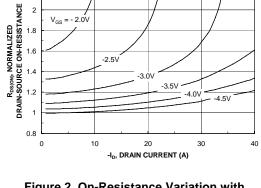


Figure 1. On-Region Characteristics.



2.2

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

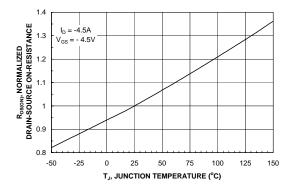


Figure 3. On-Resistance Variation with Temperature.

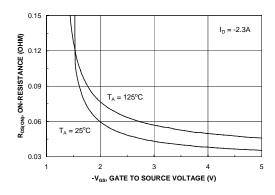


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

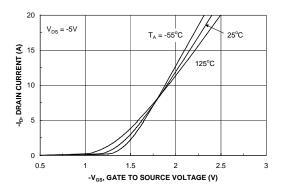


Figure 5. Transfer Characteristics.

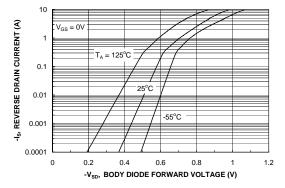
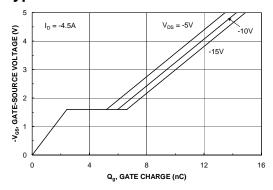


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



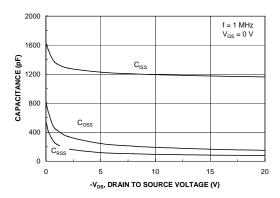
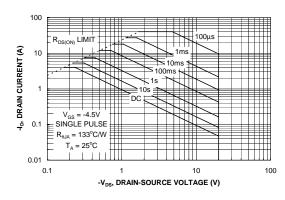


Figure 7. Gate Charge Characteristics.





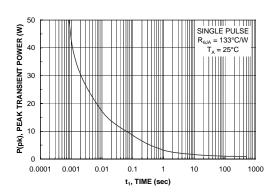


Figure 9. Maximum Safe Operating Area.



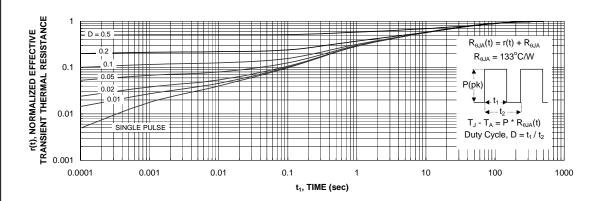


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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